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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/608,948	06/26/2003	Valery M. Dubin	42P14493	8275	
8791	7590 11/29/2005		EXAM	EXAMINER	
BLAKELY SOKOLOFF TAYLOR & ZAFMAN 12400 WILSHIRE BOULEVARD SEVENTH FLOOR			MENZ, DO	MENZ, DOUGLAS M	
			ART UNIT	PAPER NUMBER	
LOS ANGE	ELES, CA 90025-1030	2891			
			DATE MAILED: 11/29/2009	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)		
	10/608,948	DUBIN ET AL.		
Office Action Summary	Examiner	Art Unit		
	Douglas M. Menz	2891		
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address		
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period w  - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tim rill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. nely filed the mailing date of this communication. D (35 U.S.C. § 133).		
Status				
1) Responsive to communication(s) filed on 26 Se	action is non-final. ace except for formal matters, pro			
Disposition of Claims				
4) ☐ Claim(s) 1-5,7 and 8 is/are pending in the appli 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-5,7 and 8 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or Application Papers  9) ☐ The specification is objected to by the Examiner 10) ☐ The drawing(s) filed on 26 June 2003 is/are: a) Applicant may not request that any objection to the content of the con	vn from consideration.  relection requirement.  r.  ⊠ accepted or b) □ objected to	•		
Replacement drawing sheet(s) including the correcti  11) The oath or declaration is objected to by the Example 11.				
Priority under 35 U.S.C. § 119				
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No.</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>				
Attachment(s)				
Notice of References Cited (PTO-892)  Notice of Draftsperson's Patent Drawing Review (PTO-948)  Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa			

Application/Control Number: 10/608,948

Art Unit: 2891

#### **DETAILED ACTION**

### Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-2 and 7-8 are rejected under 35 U.S.C. 102(b) as being anticipated by Lur et al. (US 5413962).

Regarding claim 1, Lur discloses an apparatus comprising:

a first layer (30) having a first at least one interconnect (26) formed in an interlayer dielectric (30, Figs. 1-11 and Cols. 2-4);

a second layer (on top of 30 bound by top of 34, Fig. 2-6) formed over the first layer, the second layer having a second at least one interconnect (29, Figs.5-11), and wherein the second layer comprises a first sublayer (42, Fig. 11) and a second sublayer (85, Fig. 11), the first sublayer (42, Fig. 11) is between the first layer (30, Fig. 11) and the second sublayer (85, Fig. 11), and the second sublayer (85, Fig. 11) is between the first sublayer (42, Fig. 11) and the third layer (bound by 60 and top of 34 top of Fig. 10), the first sublayer (42, Fig. 11) comprising an ILD, and the second sublayer (85, Fig. 11) comprising air (Cols. 2-4);

a third layer (bound by 60 and top of 34 top of Fig. 10) formed over the second layer, the third layer defining at least one air gap (85, Fig. 11) between the second at least one interconnect (29, Fig. 11) and the third layer (Fig. 11 and Cols. 2-4);

and at least one shunt (40, 50) comprising a first material different from a second material of the first and second at least one interconnects (26, 29 respectively, Fig. 11) selectively covering the first and second at least one interconnects (Fig. 11).

Regarding claim 2, Lur further discloses comprising a barrier layer (42) to support the first and second at least one interconnects (Fig. 11 and Col. 4, lines: 20-30).

Regarding claim 7, Lur further discloses wherein the second at least one interconnect (29, Fig. 11) is within the second sublayer (85, Fig. 11).

Regarding claim 8, Lur further dislcoses wherein the second layer comprises air (85, Fig. 11).

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Art Unit: 2891

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

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Claims 3-5 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lur et al. (US 5413962) in view of Dubin et al. (US 6696758).

Regarding claim 3, Lur discloses the features of claim 2 as mentioned above. however, Lur does not explicitly disclose wherein the barrier layer has a thickness of between 50-500 Angstroms. Dubin discloses an interconnect structure which incorporates a barrier layer (140, Fig. 1) that has a thickness of 100-500 Angstroms (Col. 3, lines: 45-65). It would have been obvious to one of ordinary skill in the art at the time of the invention to use Dubin's barrier layer with its disclosed thickness for the purpose of inhibiting interconnect material diffusion as taught by Dubin (Col. 3, lines: 50-55).

Regarding claims 4-5, Lur discloses the apparatus of claim 1 as mentioned above and further discloses at least one via having a vial plug (26 or 29), however, Lur does not explicitly disclose further the via plug material is selected from the group consisting of cobalt and nickel or that the vial plug is deposited using electroless deposition.

Dubin discloses an interconnect structure which incorporates a via plug material that is selected from the group consisting of cobalt and nickel (Col. 5) and that the via plug is deposited using electroless deposition (Col. 7). It would have been obvious to one of ordinary skill in the art at the time of the invention to use a via plug material that is selected from the group consisting of cobalt and nickel and that the via plug is deposited using electroless deposition with Lur's structure for the purpose of improving the structural properties of the interconnect structure as taught by Dubin (Col. 2).

### Response to Arguments

Applicant's arguments with respect to claims 1-5 and 7-8 have been considered but are moot in view of the new ground(s) of rejection. Specifically, Lur discloses an interconnect structure which teaches both an ILD layer and a layer of air. Furthermore, to clarify the interpretation of the word "shunt", the examiner directs Applicant to the Webster's Collegiate Dictionary, Tenth Edition, which states that a shunt is a conductor joining two points in an electrical circuit so as to form a parallel or alternative path through which a current may pass.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas M. Menz whose telephone number is 571-272-1877. The examiner can normally be reached on M-F 8-5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Bill Baumeister can be reached on 571-272-1722. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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